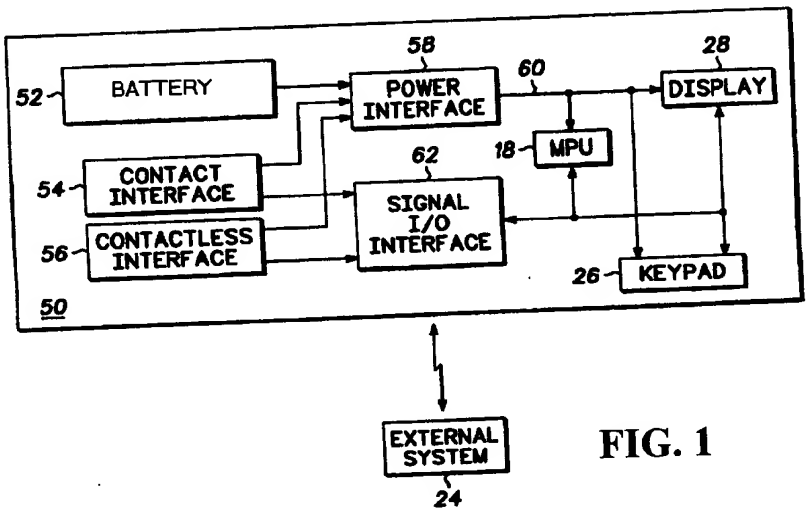
58
28
60
52
BATTERY
POWER INTERFACE
DISPLAY
18
MPU
62
54
CONTACT INTERFACE
SIGNAL I/O INTERFACE
56
CONTACTLESS INTERFACE
26
KEYPAD
50
EXTERNAL SYSTEM
24

FIG. 1

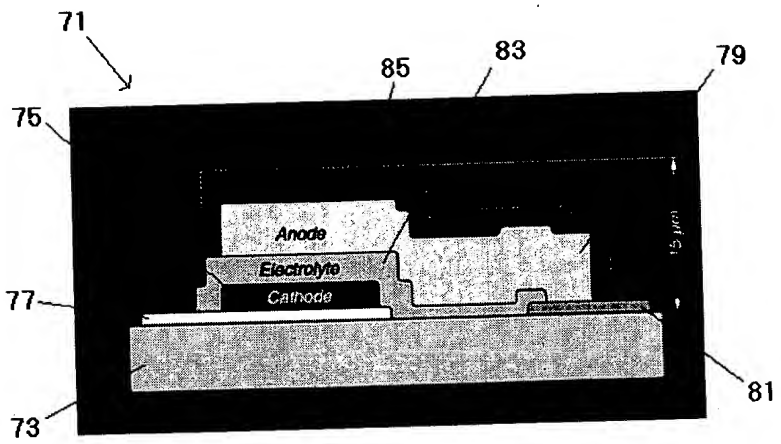

FIG. 2

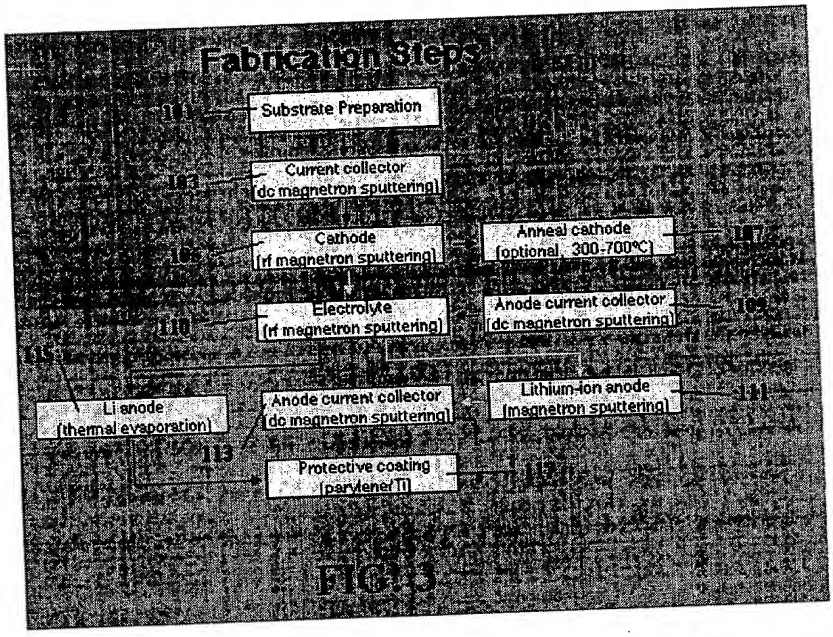
Fabrication Steps
Substrate Preparation
Current collector (dc magnetron sputtering)
Cathode (rf magnetron sputtering)
Electrolyte (rf magnetron sputtering)
Li anode (thermal evaporation)
Anode current collector (dc magnetron sputtering)
Protective coating (parylene C)
Anneal cathode (optional, 300-700°C)
Anode current collector (dc magnetron sputtering)
Lithium-ion anode (magnetron sputtering)

FIG. 3

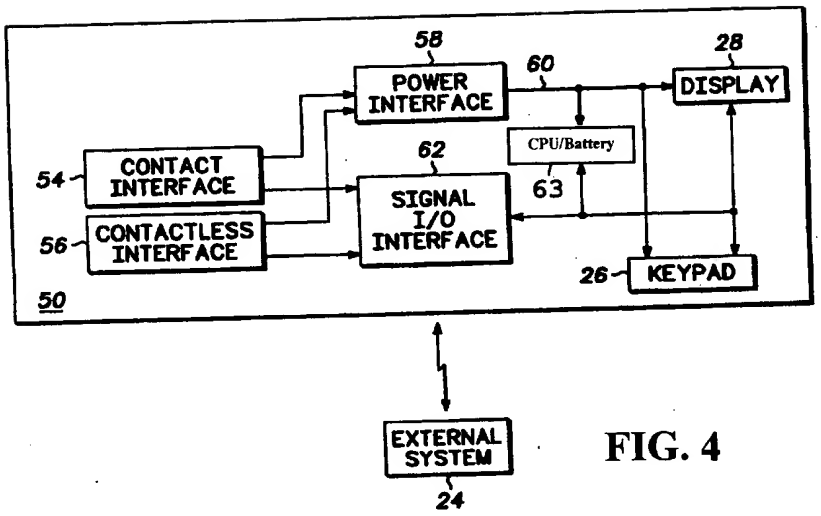
58
POWER INTERFACE
60
28
DISPLAY
CPU/Battery
62
63
54
CONTACT INTERFACE
SIGNAL I/O INTERFACE
56
CONTACTLESS INTERFACE
26
KEYPAD
50
EXTERNAL SYSTEM
24

FIG. 4

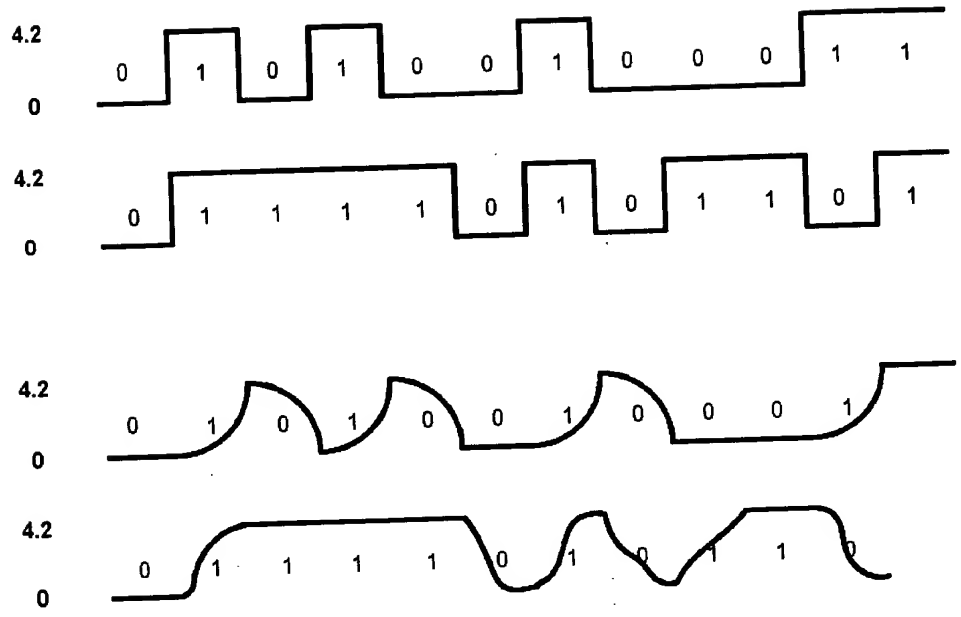
4.2
0
0 1 0 1 0 0 1 0 0 0 1 1
4.2
0
0 1 1 1 1 0 1 0 1 1 0 1
4.2
0
0 1 0 1 0 0 1 0 0 0 1
4.2
0
0 1 1 1 1 0 1 0 1 1 0

FIG 5

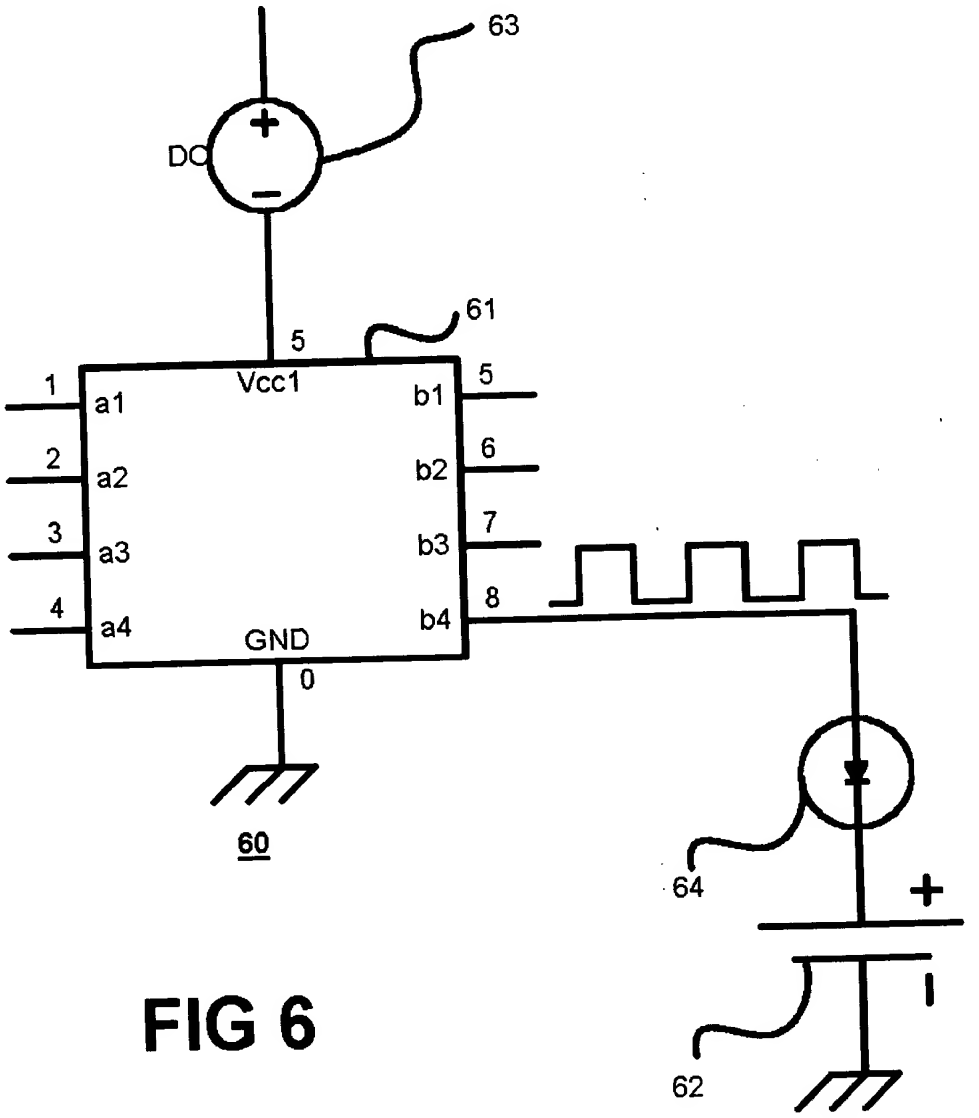

FIG 6